

## C2220X123K1TACTU

Aliases (C2220X123K1TAC7800)

**Specifications** 

Insulation Resistance

SMD Comm X8G HT150C Flex, Ceramic, 0.012 uF, 10%, 100 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	190 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	2220
L	5.9mm +/-0.75mm
W	5mm +/-0.4mm
Т	1.4mm +/-0.15mm
S	3.5mm MIN
В	0.7mm +/-0.35mm

83.3333 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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